

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	("tanida-kazumasa.in. and ((pillarshapedconnectingmember)sameopen\$3\$same semiconductor)") .PN	US-PGPUB; USPAT	OR	OFF	2009/05/12 09:37
L2	0	"tanida-kazumasa.in. and" ((pillar shaped connecting member) same open\$3 same semiconductor)	US-PGPUB; USPAT	ADJ	ON	2009/05/12 09:38
L3	0	tanida-kazumasa.in. and ((pillar shaped connecting member) same open\$3 same semiconductor)	US-PGPUB; USPAT	ADJ	ON	2009/05/12 09:38
L4	2	tanida-kazumasa.in. and ((pillar) same open\$3 same semiconductor)	US-PGPUB; USPAT	ADJ	ON	2009/05/12 09:39
L5	0	tanida-kazumasa.in. and ((pillar) same open\$3 same semiconductor).clm.	US-PGPUB; USPAT	ADJ	ON	2009/05/12 09:39
L6	0	miyata-osamu.in. and ((pillar) same open\$3 same semiconductor).clm.	US-PGPUB; USPAT	ADJ	ON	2009/05/12 09:40
L7	0	roh.m.as. and ((pillar) same open\$3 same semiconductor).clm.	US-PGPUB; USPAT	ADJ	ON	2009/05/12 09:41
S1	2730	@ad<"20040928" and "257/778".ocls.	US-PGPUB; USPAT	ADJ	ON	2008/12/03 15:53
S2	669	@ad<"20040928" and "257/778".ocls. and underfill	US-PGPUB; USPAT	ADJ	ON	2008/12/03 16:11
S3	42	@ad<"20040928" and "257/778".ocls. and underfill and (solde\$ resist)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 16:11
S4	38	tanida-kazumasa.in.	US-PGPUB; USPAT	ADJ	ON	2008/12/03 17:31
S5	26	tanida-kazumasa.in. and (seal or seal\$4)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 17:32
S6	26	tanida-kazumasa.in. and (seal or seal\$4) and surface	US-PGPUB; USPAT	ADJ	ON	2008/12/03 17:33
S7	18	tanida-kazumasa.in. and (seal or seal\$4) and surface and (open or opening)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 17:34
S8	18	tanida-kazumasa.in. and (seal or seal\$4) and surface and (open or opening or opened)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 17:37
S9	0	"miyata-osamu.in" and (seal or seal\$4) and surface and (open or opening or opened) not tanida-kazumasa.in.	US-PGPUB; USPAT	ADJ	ON	2008/12/03 17:51
S10	14	miyata-osamu.in. and (seal or seal\$4) and surface and (open or opening or opened) not tanida-kazumasa.in.	US-PGPUB; USPAT	ADJ	ON	2008/12/03 17:51
S11	432	roh.m.as. and (seal or seal\$4) and surface and (open or opening or opened) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 18:01
S12	152	roh.m.as. and semiconductor and (seal or seal\$4) and surface and (open or opening or opened) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 18:02
S13	86	roh.m.as. and (semiconductor device) and (seal or seal\$4) and surface and (open or opening or opened) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB; USPAT	ADJ	ON	2008/12/03 18:04

S14	7	rohm.as. and fill and (semiconductor device) and (seal or seal\$4) and surface and (open or opening or opened) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB, USPAT	ADJ	ON	2008/12/03 18:05
S15	16	rohm.as. and (semiconductor device) and (seal or seal\$4) and surface and ("open.clm" or opening.clm. or opened.clm.) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB, USPAT	ADJ	ON	2008/12/03 18:06
S16	28	rohm.as. and (semiconductor) and (seal or seal \$4) and surface and ("open.clm" or opening.clm. or opened.clm.) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB, USPAT	ADJ	ON	2008/12/03 18:07
S17	30	rohm.as. and (semiconductor) and (seal or seal \$4) and surface and (open.clm. or opening.clm. or opened.clm.) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB, USPAT	ADJ	ON	2008/12/03 18:07
S18	23	rohm.as. and (semiconductor) and (seal or seal \$4) and surface.clm. and (open.clm. or opening.clm. or opened.clm.) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB, USPAT	ADJ	ON	2008/12/03 18:07
S19	19	rohm.as. and (semiconductor.clm.) and (seal or seal\$4) and surface.clm. and (open.clm. or opening.clm. or opened.clm.) not (tanida-kazumasa.in. or miyata-osamu.in.)	US-PGPUB, USPAT	ADJ	ON	2008/12/03 18:07
S20	1	@ad<"20040928" and underfill and (solde\$6 resist) and decal	US-PGPUB, USPAT	ADJ	ON	2008/12/04 09:07
S21	78	@ad<"20040928" and underfill and decal	US-PGPUB, USPAT	ADJ	ON	2008/12/04 09:07
S22	74	@ad<"20040928" and underfill and decal and solder	US-PGPUB, USPAT	ADJ	ON	2008/12/04 09:08
S23	11	@ad<"20040928" and underfill and decal and (solder (resist or mask))	US-PGPUB, USPAT	ADJ	ON	2008/12/04 09:08
S24	724	@ad<"20040928" and underfill and (solder (resist or mask)) and semiconductor	US-PGPUB, USPAT	ADJ	ON	2008/12/04 09:13
S25	0	@ad<"20040928" and "257/778".ccls. and underfill and (solde\$6 (resist or mask)) and (functional (surface or side))	US-PGPUB, USPAT	ADJ	ON	2008/12/04 09:43
S26	0	@ad<"20040928" and underfill and (solde\$6 (resist or mask)) and (functional (surface or side))	US-PGPUB, USPAT	ADJ	ON	2008/12/04 09:43
S27	46	@ad<"20040928" and "257/778".ccls. and underfill and (solde\$6 (resist or mask)) and (circuitry)	US-PGPUB, USPAT	ADJ	ON	2008/12/04 09:44
S28	5	@ad<"20040928" and "257/778".ccls. and underfill and (solde\$6 (resist or mask)) and (chip circuitry)	US-PGPUB, USPAT	ADJ	ON	2008/12/04 09:44
S29	4	@ad<"20040928" and "257/778".ccls. and underfill and (solde\$6 (resist or mask)) and (chip connect)	US-PGPUB, USPAT	ADJ	ON	2008/12/04 09:46
S30	44	@ad<"20040928" and murali-venkatesan.in.	US-PGPUB, USPAT	ADJ	ON	2008/12/04 09:57
S31	0	@ad<"20040928" and sunohara-mashiro.in.	US-PGPUB, USPAT	ADJ	ON	2008/12/04 09:59
S32	26	@ad<"20040928" and sunohara-masahiro.in.	US-PGPUB, USPAT	ADJ	ON	2008/12/04 10:00

S33	1	@ad<"20040928" and "257/778".cols. and underfill and (solde\$6 (resist or mask)) and (c4 package)	US-PGPUB; USPAT	ADJ	ON	2008/12/04 10:03
S34	23	@ad<"20040928" and "257/778".cols. and underfill and (solde\$6 (resist or mask)) and (c4)	US-PGPUB; USPAT	ADJ	ON	2008/12/04 10:04
S35	1	"20080246163"	US-PGPUB; USPAT	ADJ	ON	2008/12/04 15:06
S36	0	tanida-kazumasa.in. and miyata-osamu.in.	JPO	ADJ	ON	2009/05/08 15:05
S37	0	tanida-kazumasa.in.	JPO	ADJ	ON	2009/05/08 15:05
S38	154	miyata-osamu.in.	JPO	ADJ	ON	2009/05/08 15:05
S39	7	miyata-osamu.in. and tanida.in.	JPO	ADJ	ON	2009/05/08 15:06
S40	18	miyata-osamu.in. and tanida.in.	US-PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/08 15:09
S41	2	"20030222342"	US-PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/08 15:26
S42	376	@ad<"20040928" and (flip chip) and ((wiring board) or (wiring substrate) or pcb or (printed circuit board)) and ((solder (resist or mask)) same (underfill\$2 or under-fill\$2 or fill\$3)) and (solder near (ball or pad or bond\$4 or contact \$1 or bump\$1))	US-PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/08 15:33
S43	81	@ad<"20040928" and (flip chip) and ((wiring board) or (wiring substrate) or pcb or (printed circuit board)) and ((solder (resist or mask)) same (underfill\$2 or under-fill\$2 or fill\$3)) and (solder near (ball or pad or bond\$4 or contact \$1 or bump\$1)) and column	US-PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/08 15:55
S44	1	("4548862").PN.	US-PGPUB; USPAT	OR	OFF	2009/05/08 15:59
S45	1	"20020033412"	US-PGPUB; USPAT	ADJ	ON	2009/05/08 17:07
S46	16	@ad<"20040928" and (flip chip) and ((wiring board) or (wiring substrate) or pcb or (printed circuit board)) and ((solder (resist or mask)) same (underfill\$2 or under-fill\$2 or fill\$3)) and (solder near (ball or pad or bond\$4 or contact \$1 or bump\$1)) and pillar not column	US-PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/08 17:13
S47	53	@ad<"20040928" and (flip chip) and ((wiring board) or (wiring substrate) or pcb or (printed circuit board)) and ((solder (resist or mask)) same (underfill\$2 or under-fill\$2 or fill\$3)) and (solder near (ball or pad or bond\$4 or contact \$1 or bump\$1)) and (open\$3 with (solder mask)) not column	US-PGPUB; USPAT; USCOR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/08 17:33

S48	27	@ad- "20040928" and (flip chip) and ((wiring board) or (wiring substrate) or pcb or (printed circuit board)) and ((solder (resist or mask)) same (underfill\$2 or under-fill\$2 or fill\$3)) and (solder near (ball or pad or bond\$4 or contact \$1 or bump\$1)) and (open\$3 with (solder mask)) and column	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/08 18:19
S49	2	"20040207064"	US-PGPUB; USPAT	ADJ	ON	2009/05/08 18:29
S50	1	"20040169275"	US-PGPUB; USPAT	ADJ	ON	2009/05/08 18:30
S51	771	@ad- "20040928" and (flip chip) and ((wiring board) or (wiring substrate) or pcb or (printed circuit board)) and ((solder (resist or mask)) same (open\$3 or pattern))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/08 18:40
S52	451	@ad- "20040928" and (flip chip) and ((wiring board) or (wiring substrate) or pcb or (printed circuit board)) and ((solder (resist or mask)) same (open\$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/08 18:40
S53	338	@ad- "20040928" and (flip chip) and ((wiring board) or (wiring substrate) or pcb or (printed circuit board)) and ((solder (resist or mask)) with (open\$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/08 18:41
S54	143	@ad- "20040928" and (flip chip) and ((wiring board) or (wiring substrate) or pcb or (printed circuit board)) and ((solder (resist or mask)) with (open\$3)) and (mm or mils or mil or micrometers or micrometer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/08 18:43
S55	3	("2001/0013642").URPN.	USPAT	ADJ	ON	2009/05/08 19:26
S56	4	("2002/0159243").URPN.	USPAT	ADJ	ON	2009/05/11 09:10
S57	1	("5710071").PN.	US-PGPUB; USPAT	OR	OFF	2009/05/11 11:42
S58	1	"10594561"	US-PGPUB; USPAT	ADJ	ON	2009/05/11 12:07
S59	1	"20020033412"	US-PGPUB; USPAT	ADJ	ON	2009/05/11 13:55
S60	16	09/564,382	US-PGPUB; USPAT	ADJ	ON	2009/05/11 13:57
S61	1	("6607942").PN.	US-PGPUB; USPAT	OR	OFF	2009/05/11 17:16
S62	1	"20050032273"	US-PGPUB; USPAT	ADJ	ON	2009/05/11 17:18
S63	134	@ad- "20040928" and (flip chip) and ((wiring board) or (wiring substrate) or pcb or (printed circuit board)) and ((solder (resist or mask)) same (open\$3)) and ((solder (resist or mask)) same (thick\$4)) and (" .mu. m" or mm or millimeter or millimeters or mils or mil or micrometers or micrometer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/11 17:39

S64	91	@ad<"20040928" and (flip chip) and ((wiring board) or (wiring substrate) or pcb or (printed circuit board)) and ((solder (resist or mask)) same (open\$3)) and ((solder (resist or mask)) with (thick\$4))and (" .mu.m" or mm or millimeter or millimeters or mils or mil or micrometers or micrometer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/11 17:40
S65	82	@ad<"20040928" and (flip chip) and ((wiring board) or (wiring substrate) or pcb or (printed circuit board)) and ((solder (resist or mask)) with (open\$3)) and ((solder (resist or mask)) with (thick\$4))and (" .mu.m" or mm or millimeter or millimeters or mils or mil or micrometers or micrometer)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/05/11 17:40
S66	1	("4548862").FN.	US-PGPUB; USPAT	OR	OFF	2009/05/11 17:41
S67	1	("5218234").FN.	US-PGPUB; USPAT	OR	OFF	2009/05/11 17:42

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